**1.0 Service Information:** (Fill the below)

|  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- |
| Requested date: | | |  | | |
| Sample submitted for the process of :  ( Dicing ,Wire bonding, Calibration test etc. List all process/test request) | | | | | |
| No | Process details | No. of. sample | | PASF use only | |
| Completed (Y/N) | Date |
| 1. |  |  | |  |  |
| 2. |  |  | |  |  |
| 3. |  |  | |  |  |
| 4. |  |  | |  |  |
| 5. |  |  | |  |  |
| 6. |  |  | |  |  |
| 7. |  |  | |  |  |

Remarks( if any ) **…………………………………………………………………………………….**

**……………………………………………………………………………………………………………..**

**2.0 Wafer dicing : PASF010**

Wafer /Sample material : Si / Glass/ ITO /STO / Others : ………………….

Wafer stack : Single/Bonded ( Si on Si / Si on Glass)

Wafer type : Plain / Patterned

Substrate Thickness : ………………. (in µm)

Substrate Size : 2” / 3” / 4”/ 6” , Cut pieces : …. x …. (in mm)

No.of wafer / sample : ………………...

Other specifications :

* **For plain wafer :**

Sample dicing dimension : ………… x …………. ( in mm)

Sample dicing side PR coated : Y/N

* **For Patterned wafer :**

Wafer pattern design (if any) : Y/N

Saw street width : ……………………. (in µm)

Sample dicing dimension : ……… x ……… ( in mm)

Sample dicing side PR coated : Y/N

Any information regarding the dicing requirements:

Ans:

**Note :If the wafer/sample is patterned, the user must provide the dicing layer design file.**

|  |  |  |
| --- | --- | --- |
| PASF use: | | |
| FT: | Sign: | Date: |

**3.0 Packaging/Wirebonding**

**For device to package mounting:- PASF023-PS**

Device dimension : ………… x …………. ( in mm)

Package type : PCB/ Chip carrier/ TO/ others : …………………

Type of epoxy : Thermally conductive/ Electrically conductive

No. of . Devices : ………………

Die mounting diagram (if any) : Y\* /N

**For Wire bonding: PASF005/PASF025**

Package dimension : …………….x …………. ( in mm)

Type of bonding : Wedge -Wedge /Ball -Wedge

Bond Wire : Al ( 33µm)/ Au (25µm)

Wiring diagram (if any) : Y \*/N

|  |  |  |
| --- | --- | --- |
| Bond pad specifications: | Device side | Package side |
| Metal layer  (Ex: Cr/Au :10nm/100nm) |  |  |
| Pad Dimension( in µm) |  |  |
| Pitch of Pad ( in µm) |  |  |

Any information regarding the die attach /wire bonding process requirements:

Ans:

**Note : \* If yes , user must provide the Die mounting/ Wire bonding diagram. Dummy device must require for process optimization.**

|  |  |  |
| --- | --- | --- |
| PASF use: | | |
| FT: | Sign: | Date: |